PCN Number: 202			221216012.1				P		Date:	December 21, 2022	
Title: Qualification of RFAB as an additional Fab site option for select LBC8 devices							C8 devices				
Customer Contact:			PCN Manager				D	ept:		Quality Services	
Proposed 1 st Ship Date:			Mar	20, 2023		Sample Requests accepted until:				Jan 20, 2023*	
*Sample requests received			after January 20, 2023 will not be supported.								
Change Type:											
Assembly Site		Assembly Process				<u> </u>		Assembly Materials			
Design		Electrical Specification				<u> </u>		Mechanical Specification			
Test Site		Packing/Shipping/Labeling]	<u> </u>	Test Process			
Wafer Bump SiteWafer Fab Site			Wafer Bump Material				\underline{H}	Wafer Bump Process Wafer Fab Process			
🛛 🛛 Wafer Fa	ib Site			Wafer Fab Materials Part number change					Waler Fab Process		
					Deta	-					
Description	fChange			PCI	Dela	115					
Description of Change: Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section. Current Fab Site Additional Fab Site											
	Current I		-								
Current Fal Site		cess		Vafer Imeter	New I Site	e	F	Proc	ess	Wafer Diameter	
MIHO8 LBC8			20	00mm	RFA	В	B LBC8			300mm	
Qual details are provided in the Qual Data Section.											
Reason for Change:											
Continuity of supply.											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
None.											
Changes to p	Changes to product identification resulting from this PCN:										
Fab Site Info	rmation:										
Chip Site Chip Site O			rigin C	ode (20L)	Chip	Chip Site Country Co) Chip Site City	
		MH8				JPN			Ibaraki		
RFAB			RFB			USA				Richardson	
Sample product shipping label (not actual product label) WTEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OFT: ITEM: 39 LBL: 5A (L)T0:1750 Product Affected: (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (W) TKY (1T) 7523483512 (P) 2DP REVI (2D) REVI 201 CCO: USA 201 ASO: MLA (21L) CCO: USA 201 ASO: MLA											
					T						
ISO6731DWR	ISO6731DWR ISO67				ISO67	ISO6741DWR			ISO6742DWR		
ISO6731FDWR ISO6		740FD	WR	ISO67	ISO6741FDWR			ISO6742FDWR			

Qualification Report Approve Date 12-December-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: ISO6741DWR	QBS Reference: UCC23513QDWYQ1	QBS Reference: ISO6741QDWQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0
тс	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	3/135/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	3/30/0
ESD	E2	ESD CDM	-	500 Volts	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	3/90/0

QBS: Qual By Similarity

Devices qualified at MSL2 260C: ISO6741DWR, ISO6741FDWR, ISO6742DWR, ISO6742FDWR, ISO6740DWR, ISO6740FDWR, ISO6731DWR, ISO6731FDWR

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

• The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

• The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

• The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail					
WW Change Management Team	<u>PCN ww admin team@list.ti.com</u>					

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